



FOR IMMEDIATE RELEASE

Nidec Corporation

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**Nidec Copal Develops World's Thinnest Compact, Lightweight Camera Module
for Mobile Phones**

Nidec Corporation today announces that one of its subsidiaries, Nidec Copal Corporation, has succeeded in developing the world's thinnest compact, lightweight camera module for mobile phones. Please see the attached press release from Nidec Copal Corporation for further details.

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Nidec Copal Develops World's Thinnest Compact, Lightweight 16-Megapixel Camera Module for Mobile Phones

Nidec Copal Corporation (the "Company") hereby announces that it has succeeded in developing a 4.2 mm thin—a new world record—compact, lightweight camera module for mobile phones. The new camera module has a 50% reduced volume compared to the Company's previous products. This new module, designed to meet the market need for thinner products, is a result of our technological capabilities nurtured through many years of development and manufacturing in the camera shutter and optical product fields.

The camera module features a 16-megapixel sensor—the main pixel count in the recent trend toward higher resolutions—autofocus and a bright F1.9 aperture lens. Furthermore, by adopting a high-resolution optical design adapted for the integrated compact 1.0 μ m pixel size 1/3.1" sensor, the Company has reduced the volume of the module by 50% compared to previous products, resulting in a product that combines optical performance with a thin design. Mass production is planned to start in the fall of 2016. Moving forward, the Company will continue to respond to the needs of the market by expanding their lineup of thin and compact products for mobile phones.

Specifications

- Sensor : 1/3.1" 1.0 μ m 16-megapixel CMOS
- Focal length : f3.6mm
- Maximum aperture : F1.9
- Focus distance range : 10cm~INF
- Unit size : 8.5mm (H) \times 8.5mm (W) \times 4.2mm (D)
- Weight : 0.57g

Product image

